Product Preview

Quad Bus Buffer

With 5V-Tolerant Inputs

The MC74LVX126 is an advanced high speed CMOS quad bus buffer. The inputs tolerate voltages up to 7 V, allowing the interface of 5 V systems to 3 V systems.

The MC74LVX126 requires the 3–state control input (OE) to be set Low to place the output into the high impedance state.

- High Speed: $t_{PD} = 4.4 \text{ ns}$ (Typ) at $V_{CC} = 3.3 \text{ V}$
- Low Power Dissipation: $I_{CC} = 4 \mu A \text{ (Max)}$ at $T_A = 25 \text{°C}$
- Power Down Protection Provided on Inputs
- Balanced Propagation Delays
- Low Noise: $V_{OLP} = 0.5 \text{ V (Max)}$
- Pin and Function Compatible with Other Standard Logic Families
- Latchup Performance Exceeds 300 mA
- ESD Performance: HBM > 2000 V; Machine Model > 200 V

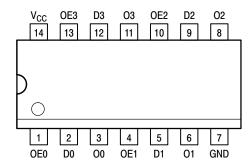


Figure 1. 14-Lead Pinout (Top View)

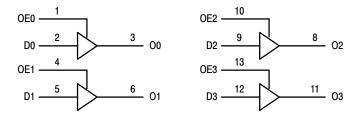


Figure 2. Logic Diagram



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14-LEAD SOIC D SUFFIX CASE 751A 14-LEAD TSSOP DT SUFFIX CASE 948G



14-LEAD SOIC EIAJ M SUFFIX CASE 965

PIN NAMES

Pins	Function
OEn Dn On	Output Enable Inputs Data Inputs 3-State Outputs

FUNCTION TABLE

INP	JTS	OUTPUTS
OEn	Dn	On
Н	L	L
Н	Н	Н
L	X	Z

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs

ORDERING INFORMATION

Device	Package	Shipping
MC74LVX126D	SOIC	55 Units/Rail
MC74LVX126M	SOIC EIAJ	50 Units/Rail

DEVICE MARKING INFORMATION

For detailed package marking information, see the Marking Diagram section on page 4 of this data sheet.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{in}	DC Input Voltage	-0.5 to +7.0	V
V _{out}	DC Output Voltage	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Diode Current	-20	mA
I _{OK}	Output Diode Current	±20	mA
l _{out}	DC Output Current, per Pin	±25	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±50	mA
P _D	Power Dissipation	180	mW
T _{stg}	Storage Temperature	-65 to +150	°C

^{*} Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	3.6	V
V _{in}	DC Input Voltage	0	5.5	V
V _{out}	DC Output Voltage	0	V _{CC}	V
T _A	Operating Temperature, All Package Types	-40	+125	°C
Δt/ΔV	Input Rise and Fall Time	0	100	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC} T _A = 25°C			C	T _A = ≤ 85°C		T _A = ≤ 125°C		
Symbol	Parameter	Test Conditions	V	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		2.0 3.0 3.6	1.5 2.0 2.4			1.5 2.0 2.4		1.5 2.0 2.4		V
V _{IL}	Low-Level Input Voltage		2.0 3.0 3.6			0.5 0.8 0.8		0.5 0.8 0.8		0.5 0.8 0.8	V
V _{OH}	High-Level Output Voltage (V _{in} = V _{IH} or V _{IL})	$I_{OH} = -50 \mu A$ $I_{OH} = -50 \mu A$ $I_{OH} = -4 \text{ mA}$	2.0 3.0 3.0	1.9 2.9 2.58	2.0 3.0		1.9 2.9 2.48			1.9 2.9 2.34	V
V _{OL}	Low-Level Output Voltage (V _{in} = V _{IH} or V _{IL})	$I_{OL} = 50 \mu A$ $I_{OL} = 50 \mu A$ $I_{OL} = 4 \text{ mA}$	2.0 3.0 3.0		0.0 0.0	0.1 0.1 0.36		0.1 0.1 0.44		0.1 0.1 0.52	V
I _{in}	Input Leakage Current	V _{in} = 5.5 V or GND	3.6			±0.1		±1.0		±1.0	μΑ
l _{OZ}	Maximum Three–State Leakage Current	$V_{in} = V_{IL} \text{ or } V_{IH}$ $V_{out} = V_{CC} \text{ or GND}$	3.6			±0.25		±2.5		±5.0	μΑ
I _{CC}	Quiescent Supply Current	$V_{in} = V_{CC}$ or GND	3.6			4.0		40		40	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0 \text{ ns}$)

					Γ _A = 25°C	;	T _A = ≤ 85°C		T _A = ≤ 125°C		
Symbol	Parameter	Test Condi	tions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay Input to Output	V _{CC} = 2.7 V	C _L = 15 pF C _L = 50 pF		5.5 7.5	10.1 13.6	1.0 1.0	13.5 17.0	1.0 1.0	15.0 19.0	ns
		$V_{CC} = 3.3 \pm 0.3 \text{ V}$	$C_L = 15 pF$ $C_L = 50 pF$		3.9 5.9	6.2 9.7	1.0 1.0	8.5 12.0	1.0 1.0	11.0 14.0	
t _{PZL} , t _{PZH}	Output Enable Time OE to O	$V_{CC} = 2.7 \text{ V}$ $R_L = 1 \text{ k}\Omega$	$C_L = 15 pF$ $C_L = 50 pF$		5.3 7.8	9.3 12.8	1.0 1.0	12.5 16.0	1.0 1.0	15.5 18.5	ns
		$V_{CC} = 3.3 \pm 0.3 \text{ V}$ $R_L = 1 \text{ k}\Omega$	$C_L = 15 pF$ $C_L = 50 pF$		4.0 6.5	5.6 9.1	1.0 1.0	7.5 11.0	1.0 1.0	9.5 13.0	
t _{PLZ} , t _{PHZ}	Output Disable Time OE to O	$V_{CC} = 2.7 \text{ V}$ $R_L = 1 \text{ k}\Omega$	C _L = 50 pF		10.0	15.7	1.0	19.0	1.0	21.0	MHz
		V_{CC} = 3.3 \pm 0.3 V R_L =1 $k\Omega$	C _L = 50 pF		8.3	11.2	1.0	13.0	1.0	15.0	
t _{OSHL} t _{OSLH}	Output–to–Output Skew (Note 1)	$V_{CC} = 2.7 \text{ V}$ $V_{CC} = 3.3 \pm 0.3 \text{ V}$	$C_L = 50 \text{ pF}$ $C_L = 50 \text{ pF}$			1.5 1.5		1.5 1.5		1.5 1.5	ns

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

		T _A = 25°C		$T_A = \le 85^{\circ}C$ T_A		T _A = ≤	T _A = ≤ 125°C		
Symbol	Parameter	Min	Тур	Max	Min	Max	Min	Max	Unit
C _{in}	Input Capacitance		4	10		10		10	pF
C _{out}	Maximum Three–State Output Capacitance		6						pF
C _{PD}	Power Dissipation Capacitance (Note 2)		14						pF

C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}/4 (per bit). C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

$\textbf{NOISE CHARACTERISTICS} \text{ (Input } t_{\text{f}} = t_{\text{f}} = 3.0 \text{ ns, } C_{\text{L}} = 50 \text{ pF, } V_{\text{CC}} = 3.3 \text{ V, Measured in SOIC Package)}$

		T _A = 25°C		
Symbol	Characteristic	Тур	Max	Unit
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	0.3	0.5	V
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	-0.3	-0.5	V
V_{IHD}	Minimum High Level Dynamic Input Voltage		2.0	V
V_{ILD}	Maximum Low Level Dynamic Input Voltage		0.8	V

SWITCHING WAVEFORMS

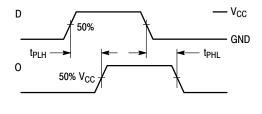


Figure 3.

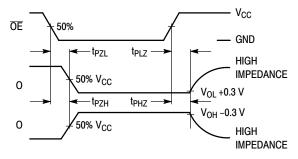
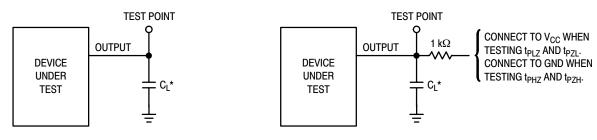


Figure 4.

TEST CIRCUITS



^{*}Includes all probe and jig capacitance

*Includes all probe and jig capacitance

Figure 5. Propagation Delay Test Circuit

Figure 6. Three-State Test Circuit

MARKING DIAGRAMS (Top View) 14 13 12 11 10 9 8 14 12 11 10 9 8 13 LVX LVX126 126 AWLYWW* ALYW* 1 2 3 4 5 6 7 1 2 3 4 5 6 7 14-LEAD SOIC 14-LEAD TSSOP **D SUFFIX DT SUFFIX** CASE 751A **CASE 948G** 12 11 10 14 13 9 LVX126 AWLYWW* 1 2 3 4 5 6

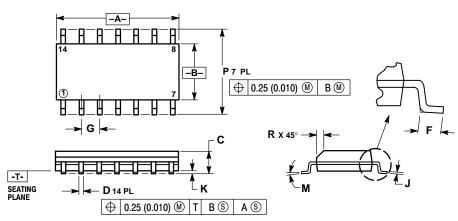
*See Applications Note #AND8004/D for date code and traceability information.

14-LEAD SOIC EIAJ M SUFFIX CASE 965

PACKAGE DIMENSIONS

D SUFFIX

PLASTIC SOIC PACKAGE CASE 751A-03 ISSUE F



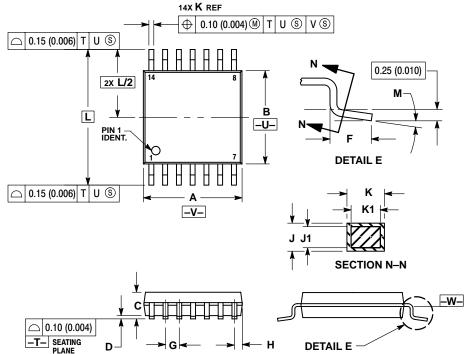
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS I			HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

DT SUFFIX

PLASTIC TSSOP PACKAGE CASE 948G-01 **ISSUE O**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION BODES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 DIMENSION O SHOLL NOT EXCEED 0.25 (0.010) PER SIDE.
 DIMENSION LODES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR

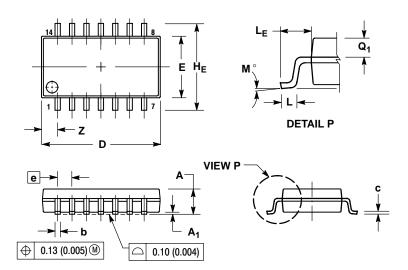
- MAI EHIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED
 AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
M	0°	8°	0°	8°	

PACKAGE DIMENSIONS

M SUFFIX

PLASTIC SOIC EIAJ PACKAGE CASE 965-01 **ISSUE O**



NOTES:

- OTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

			INCHES			
	MILLIN	IETERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α		2.05		0.081		
A ₁	0.05	0.20	0.002	0.008		
b	0.35	0.50	0.014	0.020		
С	0.18	0.27	0.007	0.011		
D	9.90	10.50	0.390	0.413		
Е	5.10	5.45	0.201	0.215		
е	1.27	BSC	0.050	BSC		
HE	7.40	8.20	0.291	0.323		
0.50	0.50	0.85	0.020	0.033		
LE	1.10	1.50	0.043	0.059		
M	0 °	10°	0°	10°		
Q ₁	0.70	0.90	0.028	0.035		
Z		1.42		0.056		

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